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### Vishay Semiconductors

<b>ELECTRICAL SPECIFICATIONS PER LEG</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA	1200	-	-				
Maximum forward voltage		I <sub>F</sub> = 16 A		-	2.5	3.0	V		
	V <sub>FM</sub>	I <sub>F</sub> = 32 A	See fig. 1	-	3.2	3.93			
		I <sub>F</sub> = 16 A, T <sub>J</sub> = 125 °C		-	2.3	2.7			
Maximum reverse	I <sub>RM</sub>	$V_R = V_R$ rated	See fig. 2	-	0.75	20	μA		
leakage current		$T_J = 125 \text{ °C}, V_R = 0.8 \text{ x } V_R \text{ rated}$	See lig. 2	-	375	2000			
Junction capacitance	CT	V <sub>R</sub> = 200 V See fig. 3		-	27	40	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from p	-	8.0	-	nH			

<b>DYNAMIC RECOVERY CHARACTERISTICS PER LEG</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
Reverse recovery time See fig. 5, 10	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200$	-	30	-					
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	90	135	ns			
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	164	245				
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 16 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	5.8	10	A			
See fig. 6	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	8.3	15				
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	260	675				
See fig. 7	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	680	1838	nc			
Peak rate of fall of recovery current during t <sub>b</sub> See fig. 8	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	120	-	A/µs			
	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	76	-				

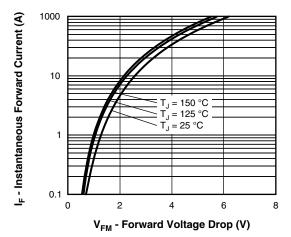
THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	MIN.	TYP.	MAX.	UNITS					
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C			
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	0.83				
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	80	K/W			
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.50	-				
Weight			-	2.0	-	g			
Weight			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Marking device		Case style TO-247AC (JEDEC)	HFA32PA120C						

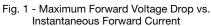
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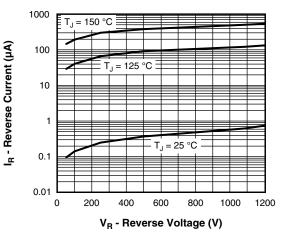
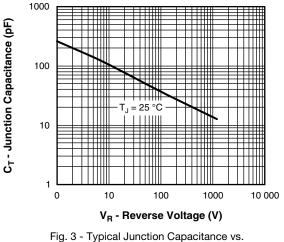
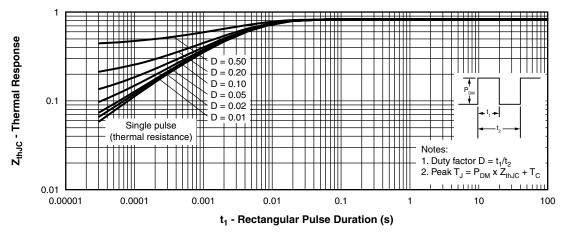


Fig. 2 - Typical Reverse Current vs. Reverse Voltage



ig. 3 - Typical Junction Capacitance v Reverse Voltage





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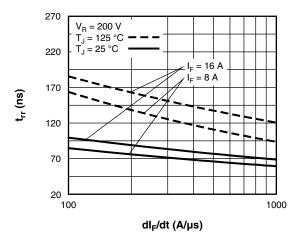


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

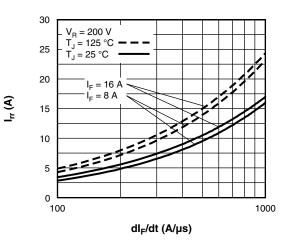


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

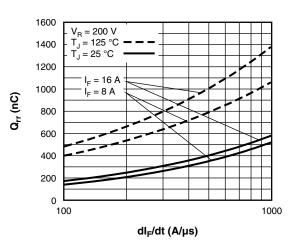
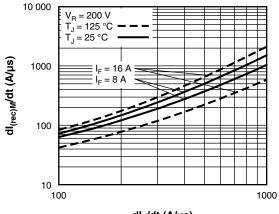


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)



dl<sub>F</sub>/dt (A/µs)

Fig. 8 - Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)

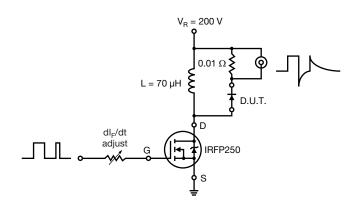


Fig. 9 - Reverse Recovery Parameter Test Circuit

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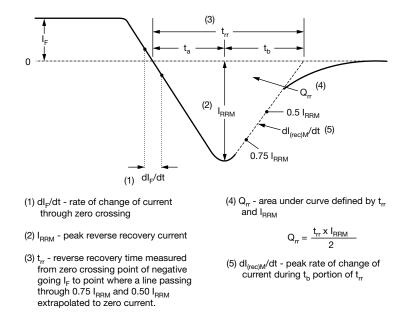
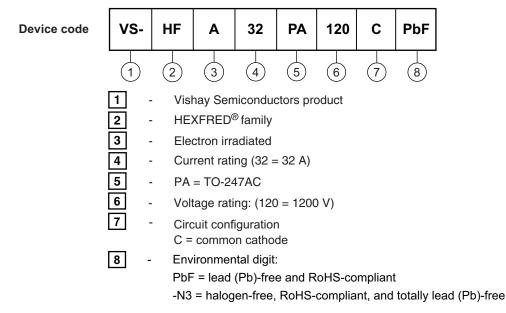


Fig. 10 - Reverse Recovery Waveform and Definitions

### **ORDERING INFORMATION TABLE**



ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-HFA32PA120CPbF	25	500	Antistatic plastic tube						
VS-HFA32PA120C-N3	25	500	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS							
Dimensions		www.vishay.com/doc?95542					
Part marking information	TO-247ACPbF	www.vishay.com/doc?95226					
	TO-247AC-N3	www.vishay.com/doc?95007					

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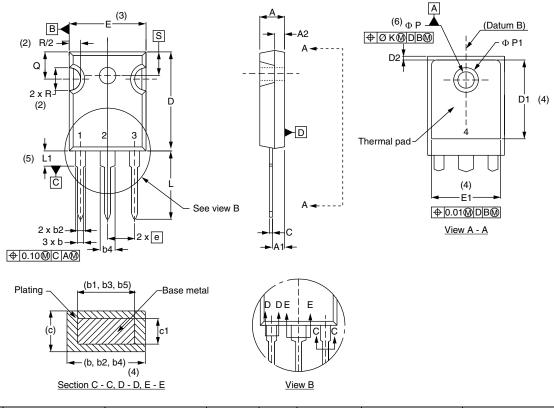
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TO-247AC - 50 mils L/F

### **DIMENSIONS** in millimeters and inches



SYMBOL MILLIN	MILLIMETERS	INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES		
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.65	5.31	0.183	0.209			D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102			E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054			E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055			е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053			ØК	0.2	254	0.0	)10	
b2	1.65	2.39	0.065	0.094			L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092			L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135			ØР	3.56	3.66	0.14	0.144	
b5	2.59	3.38	0.102	0.133			Ø P1	-	7.39	-	0.291	
С	0.38	0.89	0.015	0.035			Q	5.31	5.69	0.209	0.224	
c1	0.38	0.84	0.015	0.033			R	4.52	5.49	0.178	0.216	
D	19.71	20.70	0.776	0.815	3		S	5.51	BSC	0.217	BSC	
D1	13.08	-	0.515	-	4							

#### Notes

<sup>(1)</sup> Dimensioning and tolerancing per ASME Y14.5M-1994

(2) Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

(4) Thermal pad contour optional with dimensions D1 and E1

<sup>(5)</sup> Lead finish uncontrolled in L1

<sup>(6)</sup> Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")

<sup>(7)</sup> Outline conforms to JEDEC<sup>®</sup> outline TO-247 with exception of dimension c and Q

Revision: 20-Apr-17

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